



Product/Process Change Notice - PCN 09_0243 Rev. -

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: AD8675 Product Revision
Publication Date: 21-Dec-2009
Samples Available Date: 06-Nov-2009
Effectivity Date: 21-Mar-2010 (*the earliest date that a customer could expect to receive changed material*)

Revision Description:

Initial Release

Description Of Change

- * The Thin Film Mask was changed to increase a single passive resistor size on the setup biasing structure.
- * The following datasheet electrical parameters were updated: VOH / VOL / IVR / CMRR / AVO. Attachment #2 summarizes these changes.
- * Polyimide was added for die stress reduction, in accordance to Qual Plan 6896, and PCN 07_0024.
- * The Molding Compound and Die Attach for the MSOP was transitioned from an obsolete LSA material set to ADI's standard platform of 6600H and 84-1, in accordance to PCN 07_0024.

Reason For Change

The Thin Film mask change improves the performance of the supply current at elevated temperatures. Only a single resistor was changed in the bias setup circuitry. This change was already implemented on the AD8676, the dual version.

The Datasheet changes properly represent the parts performance as currently manufactured. These corrections and additions bring the AD8675 in-line AD8676 changes that have occurred in PCN 08-0036. Datasheet graphs were also updated to reflect the correct performance.

Polyimide is a stress relief agent which improves the device performance from external stress points. Stress relief is applied to all AD8675 packages.

The MSOP molding compound expired as noted in PCN 07_0024. The conversion to 6600H and 84-1 BOM improves the product manufacturability.

Impact of the change (positive or negative) on fit, form, function & reliability

This is positive change to the manufacturability of the product. These corrections properly reflect what can be expected from the product.

Product Identification (*this section will describe how to identify the changed material*)

Material with date code 0940 or later will be affected.

Summary of Supporting Information

The changes will be reflected in Rev B of the AD8675 datasheet. See attached Reliability Report - RQR05240 - Attachment #1.

Supporting Documents

Attachment 1:

ADI_PCN_09_0243_Rev_-_RQR05240.pdf

Attachment 2:

ADI_PCN_09_0243_Rev_-_AD8675 Table Changes 11-16-09.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (5)

AD8675 / AD8675ARMZ	AD8675 / AD8675ARMZ-REEL	AD8675 / AD8675ARZ	AD8675 / AD8675ARZ-REEL	AD8675 / AD8675ARZ-REEL7
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Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	21-Dec-2009	Initial Release

Analog Devices, Inc.

DocId:915 Parent DocId:None Layout Rev:1